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02892321 **Image available**
RESIST REMOVING APPARATUS

PUB. NO.: 01-189921 [JP 1189921 A]
PUBLISHED: July 31, 1989 (19890731)
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APPL. NO.: 63-016127 [JP 8816127]
FILED: January 26, 1988 (19880126)
INTL CLASS: [4] H01L-021/30; G03C-011/00; G03F-007/00
JAPIO CLASS: 42.2 (ELECTRONICS -- Solid State Components); 29.1 (PRECISION
 INSTRUMENTS -- Photography & Cinematography)
JOURNAL: Section: E, Section No. 838, Vol. 13, No. 481, Pg. 127,
 October 31, 1989 (19891031)

ABSTRACT

PURPOSE: To prevent decrease of concentration of hydrogen peroxide solution and to enable resist to be removed stably, by dissolving ozon gas in a heated mixture of sulfuric acid and the hydrogen peroxide solution.

CONSTITUTION: Liquid mixture 2 consisting of concentrated sulfuric acid and hydrogen peroxide in proportions of about 4:1 is introduced into a chemical vessel 1 and heated by a heater 3 to a temperature of 100-130 deg.C. Then, ozon gas 4 is fed into the liquid from a bubbler 5. Bubbles of the ozon gas produced thereby are contacted with the heated liquid mixture 2 of the concentrated sulfuric acid and hydrogen peroxide, and a part of the ozon gas is dissolved in the solution. A wafer having resist thereon is dipped in the solution for about 15 minutes, whereby the resist is removed from the wafer. The resist removing solution may be substituted by a mixture of concentrated sulfuric acid and concentrated nitric acid. According to this method, deterioration of capability of removing the resist can be prevented effectively.

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